

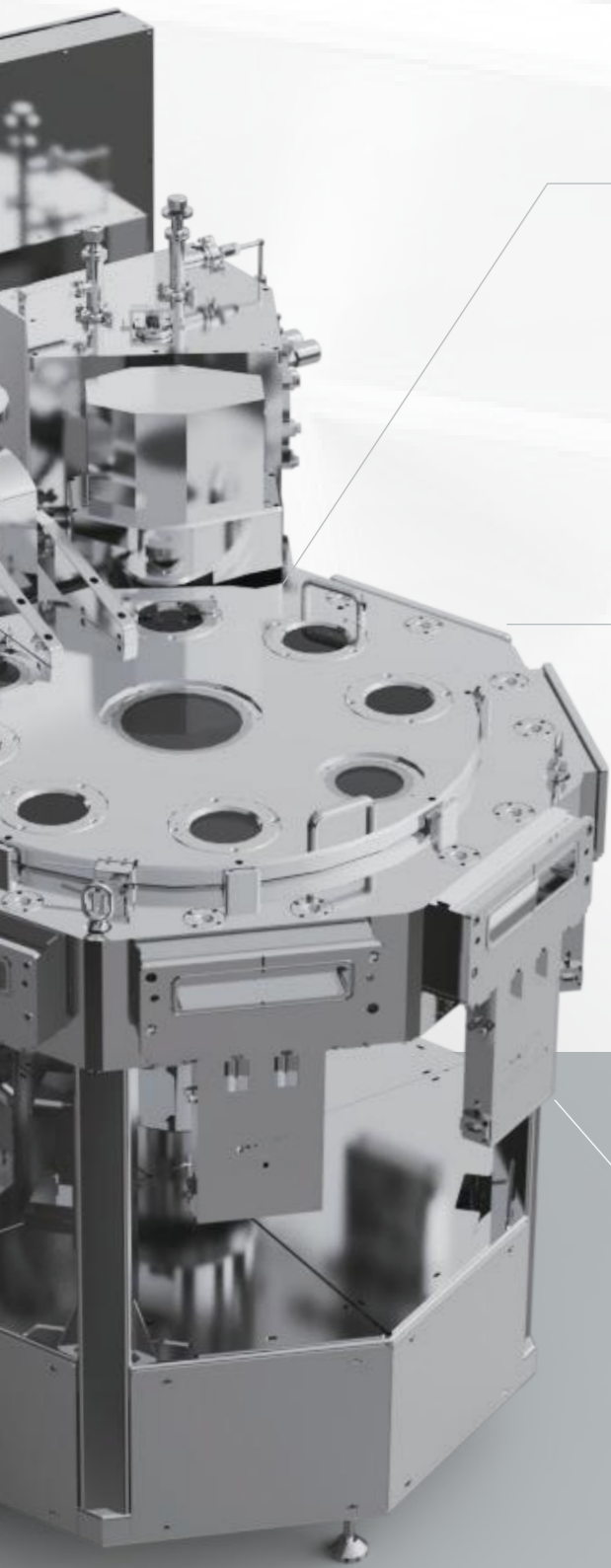
- EFEM /SMIF can be optionally equipped at the equipment front end, with EFEM offering standard and custom types.
- Vacuum mechanical arms can be selected with different models and end effectors according to actual operating conditions.
- Load Lock can be chosen with different structures and transfer methods.
- Transfer chambers & Load Lock can include optional built-in directional / cooling / pre-heating modules.
- Customized transfer chambers can be made according to actual process chamber requirements.
- Optional features include AWC functionality, Buffer functionality, wafer storage modules.


CUSTOM INFO			
Company name		Company Add.	
Contact person		Postition	
Phone number		E-mali	

CUSTOM REQUIREMENTS CONFIG	
Process equipment type	<input type="checkbox"/> PVD <input type="checkbox"/> CVD <input type="checkbox"/> ALD <input type="checkbox"/> EBL <input type="checkbox"/> Etch <input type="checkbox"/> Other _____
Wafer & Carrier Spec	Wafer Size <input type="checkbox"/> 150mm (6 ") <input type="checkbox"/> 200mm (8 ") <input type="checkbox"/> 300mm (12 ") <input type="checkbox"/> Other _____ mm
	Wafer Type <input type="checkbox"/> Normal _____ μm <input type="checkbox"/> TAIKO _____ μm <input type="checkbox"/> Other _____ Thickness _____ μm
	Wafer Material <input type="checkbox"/> Si <input type="checkbox"/> SiC <input type="checkbox"/> Glass <input type="checkbox"/> Other _____ μm
	Carrier Type <input type="checkbox"/> FOUF/FOSB ( SEMI ) <input type="checkbox"/> SMIF POD <input type="checkbox"/> Open Cassette <input type="checkbox"/> Other _____
	Carrier Spec. Maker _____ Model _____
	Carrier Feeding <input type="checkbox"/> Operator <input type="checkbox"/> AGV <input type="checkbox"/> OHT <input type="checkbox"/> Other _____
Transfer Moudle Spec	Primary Equipment
	Cleanness <input type="checkbox"/> ISO - Class 3 <input type="checkbox"/> Other _____
	Docking PM Qty <input type="checkbox"/> 1 <input type="checkbox"/> 3 <input type="checkbox"/> 4 <input type="checkbox"/> Other _____
	Docking Load Lock Qty <input type="checkbox"/> 1 <input type="checkbox"/> 2 <input type="checkbox"/> Other _____
	Front-end Equipment <input type="checkbox"/> EFEM <input type="checkbox"/> SMIF <input type="checkbox"/> None-opention <input type="checkbox"/> Other _____


**Note**

Please fill out this form with the assistance of your account manager.




 Independent research and development and production of core hardware and software.

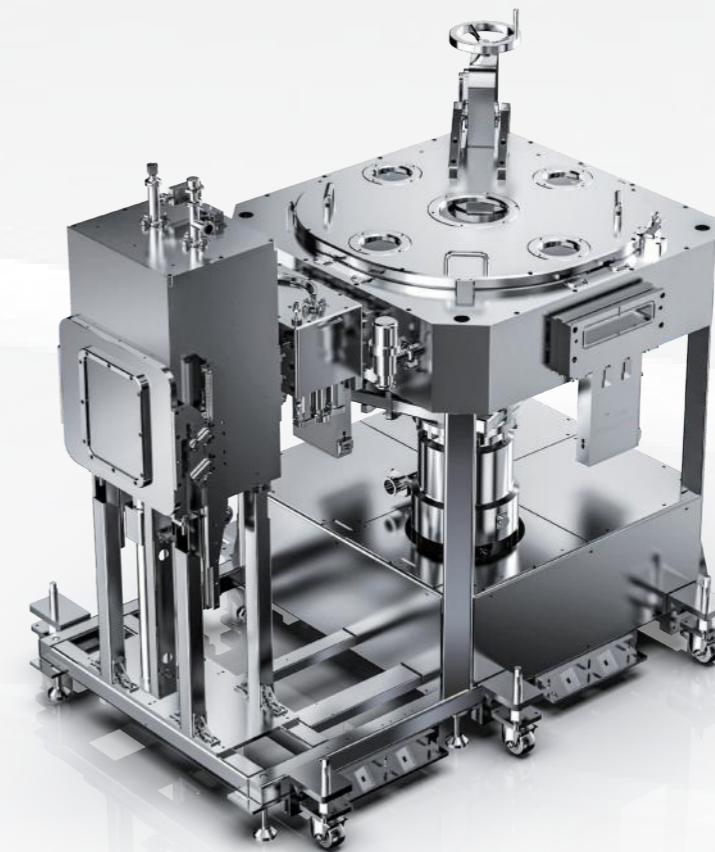
The core components of the vacuum transfer system are independently designed and developed by Fortrend, and assembled and produced at its own production base, achieving better delivery times and performance.

 Deeply rooted in the semiconductor field for many years, adaptable to most semiconductor front-end process equipment.

Fortrend has been deeply involved in the semiconductor transport field for over forty years, with equipment adapted to most semiconductor front-end processes. All production equipment complies with SEMI standards and adapts to the process requirements of various semiconductor/microelectronic material processing equipment, such as wafers/masks.

 Providing standardized modules and customized solutions to meet different requirements.

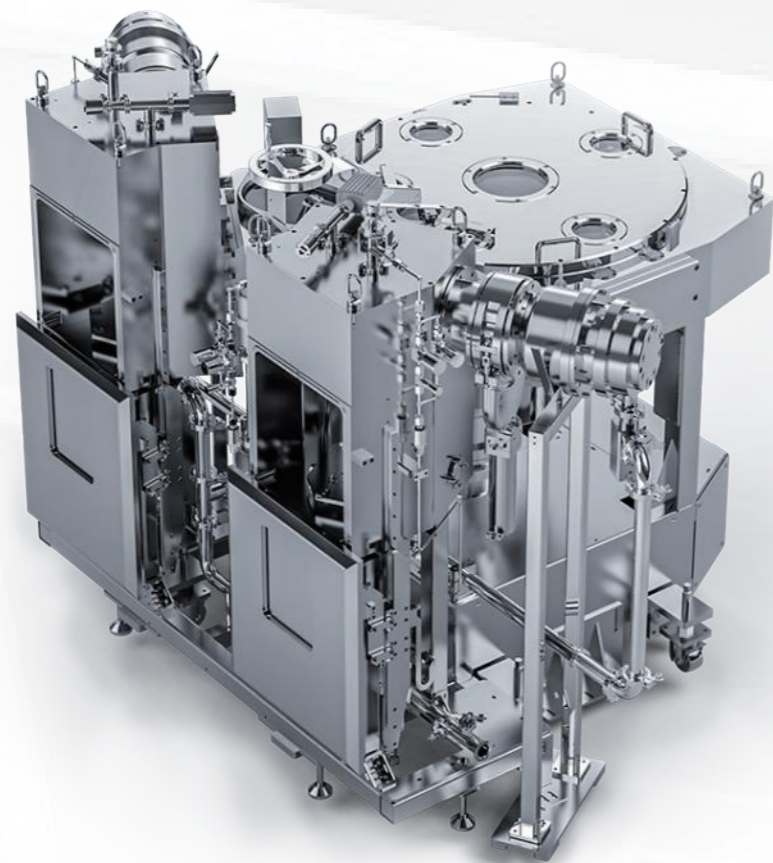
Fortrend vacuum transfer systems can provide standard solutions for process equipment integration and can also be customized according to customer requirements. Both software and hardware have mature solutions to choose from, meeting the needs of different process equipment and actual operating conditions.



**Quadrilateral Wafer Vacuum Transfer Platform**

 SUITABLE FOR

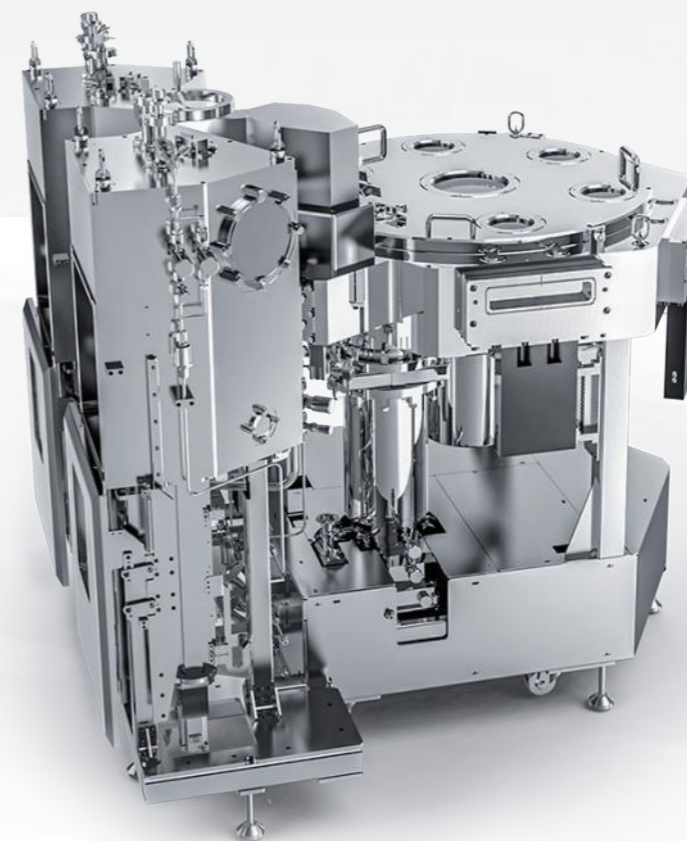
- Wafers up to 200mm (including TAIKO, frame wafers), masks, and general semiconductor materials (such as photovoltaic silicon wafers, etc.)
- PVD, CVD, ALD, and other semiconductor front-end / general semiconductor process equipment.
- High cleanliness transmission, wafer surface cleanliness Class 1.
- Efficient and stable transmission, with a transmission efficiency of  $\geq 200$  pcs/h; Up time:  $\geq 98\%$ .
- Support localization substitution and customized customization.




Pentagon Wafer Vacuum Transfer Platform

 SUITABLE FOR

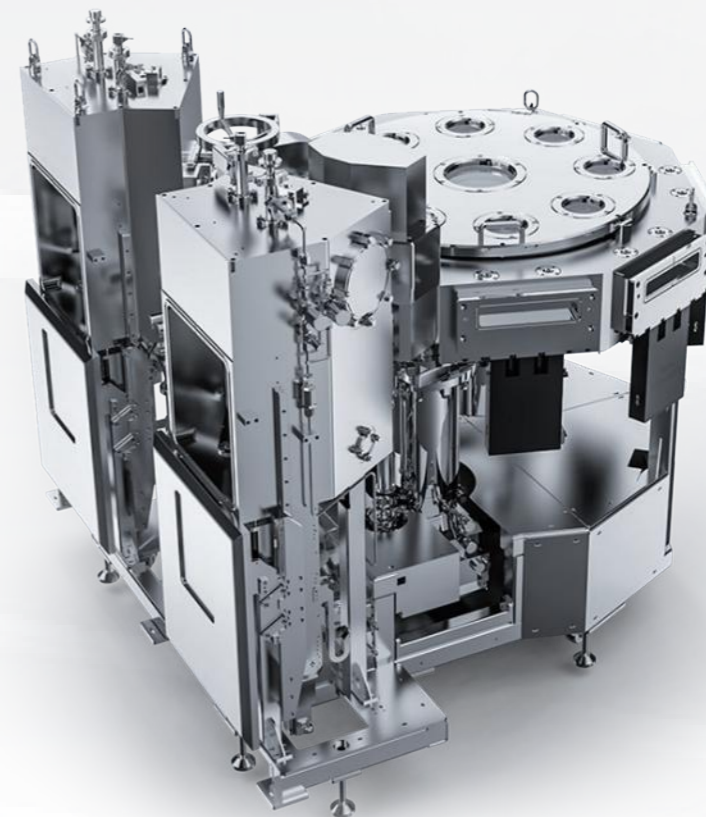
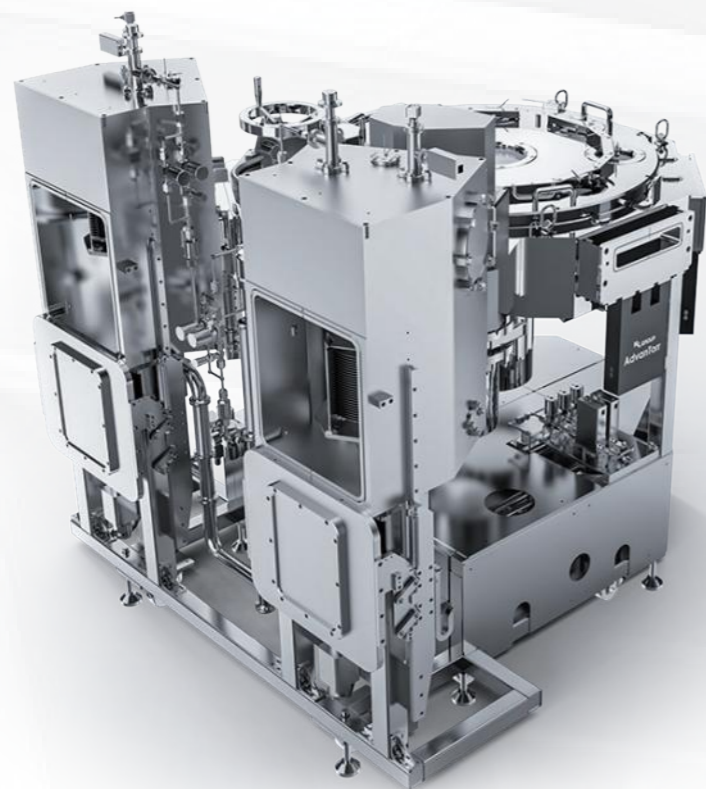
- Wafers up to 200mm (including TAIKO, frame wafers), masks, and general semiconductor materials (such as photovoltaic silicon wafers, etc.)
- PVD, CVD, ALD, and other semiconductor front-end / general semiconductor process equipment.
- High cleanliness transmission, wafer surface cleanliness Class 1.
- Efficient and stable transmission, with a transmission efficiency of  $\geq 200$  pcs/h; Up time:  $\geq 98\%$ .
- Support localization substitution and customized customization.




Hexagon Wafer Vacuum Transfer Platform

 SUITABLE FOR


- Wafers up to 200mm (including TAIKO, framewafers), masks, and general semiconductor materials (such as photovoltaic silicon wafers, etc.)
- PVD, CVD, ALD, and other semiconductor front-end / general semiconductor process equipment.
- High cleanliness transmission, wafer surface cleanliness Class 1.
- Efficient and stable transmission, with a transmission efficiency of  $\geq 200$  pcs/h; Up time:  $\geq 98\%$ .
- Support localization substitution and customized customization.

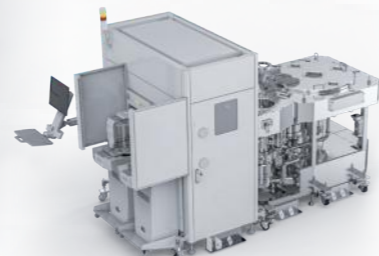
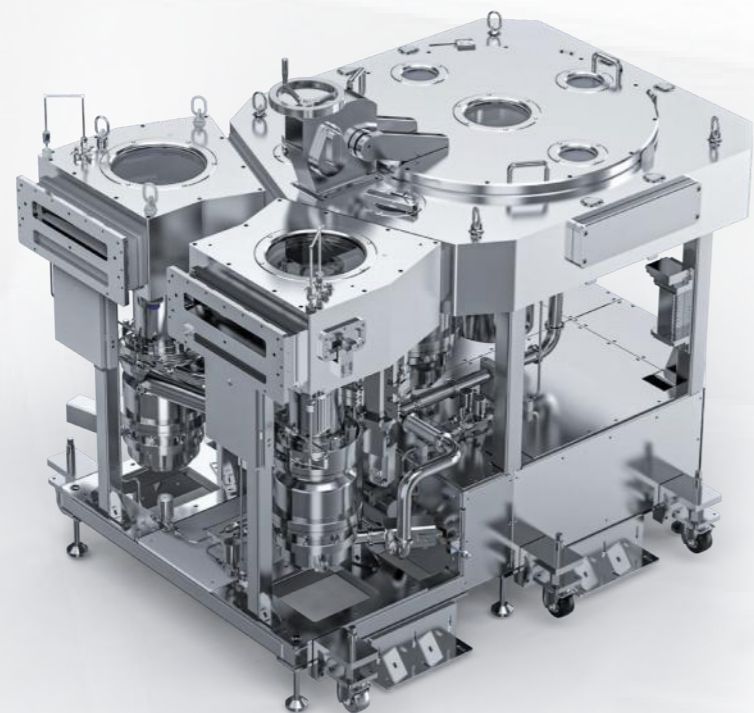


### Heptagon Wafer Vacuum Transfer Platform

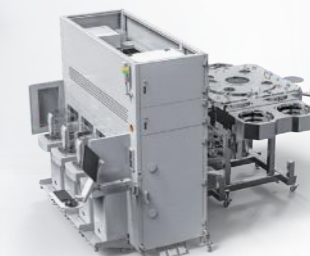
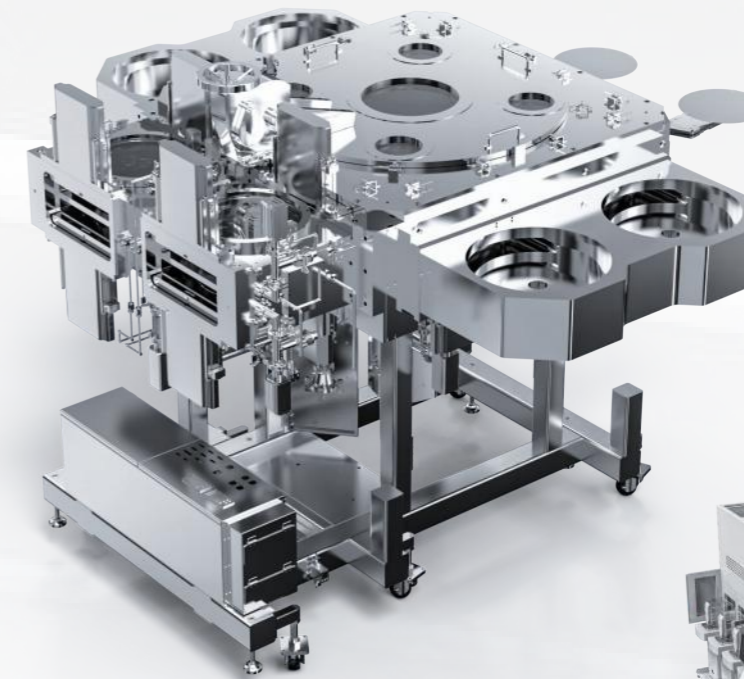
-  **SUITABLE FOR**
- Wafers up to 200mm (including TAIKO, frame wafers), masks, and general semiconductor materials (such as photovoltaic silicon wafers, etc.)
  - PVD, CVD, ALD, and other semiconductor front-end / general semiconductor process equipment.
  - High cleanliness transmission, wafer surface cleanliness Class 1.
  - Efficient and stable transmission, with a transmission efficiency of  $\geq 200$  pcs/h; Up time:  $\geq 98\%$ .
  - Support localization substitution and customized customization.

### Octagon Wafer Vacuum Transfer Platform

-  **SUITABLE FOR**
- Wafers up to 200mm (including TAIKO, frame wafers), masks, and general semiconductor materials (such as photovoltaic silicon wafers, etc.)
  - PVD, CVD, ALD, and other semiconductor front-end / general semiconductor process equipment.
  - High cleanliness transmission, wafer surface cleanliness Class 1.
  - Efficient and stable transmission, with a transmission efficiency of  $\geq 200$  pcs/h; Up time:  $\geq 98\%$ .
  - Support localization substitution and customized customization.



Customized - Pentagonal Standard Vacuum Transfer System (12-inch Wafer)



Customized - 12-inch Dual-Feed Vacuum Transfer Module

### Pentagonal Standard Vacuum Transfer System (12-inch wafer)

#### SUITABLE FOR

- Wafers up to 300mm (including TAIKO, frame wafers), masks, and general semiconductor materials (such as photovoltaic silicon wafers, etc.)
- PVD, CVD, ALD, and other semiconductor front-end / general semiconductor process equipment.
- High cleanliness transmission, wafer surface cleanliness Class 1.
- Efficient and stable transmission, with a transmission efficiency of  $\geq 200$  pcs/h; Up time:  $\geq 98\%$ .
- Support localization substitution and customized customization.

### Dual-Feed Wafer Vacuum Transfer Platform

#### SUITABLE FOR

- Wafers up to 300mm (including TAIKO, frame wafers), masks, and general semiconductor materials (such as photovoltaic silicon wafers, etc.)
- PVD, CVD, ALD, and other semiconductor front-end / general semiconductor process equipment.
- High cleanliness transmission, wafer surface cleanliness Class 1.
- Efficient and stable transmission, with a transmission efficiency of  $\geq 200$  pcs/h; Up time:  $\geq 98\%$ .
- Support localization substitution and customized customization.